

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. TI-37214		SERIAL NO. 10/826,713	
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT: William D. Boyd			
FILING DATE 04/16/2004				GROUP 2826			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)	
BPS	US 6,784,539 B2	08/2004	Efland	257	712		
	US 6,597,065 B1	07/2003	Efland	257	712		
	US 6,683,380 B2	01/2004	Efland et al.	257	734		
FOREIGN PATENT DOCUMENTS							
DOCUMENT NUMBER	DATE	COUNTRY	NAME	CLASS/SUBCLASS			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
BPS	Appl. Serial Number 11/358,668, TI Docket Number TI-39973 "Flip Chip Package with Advanced Electrical and Thermal Properties for High Current Designs", William D. Boyd et al.						
EXAMINER				DATE CONSIDERED			